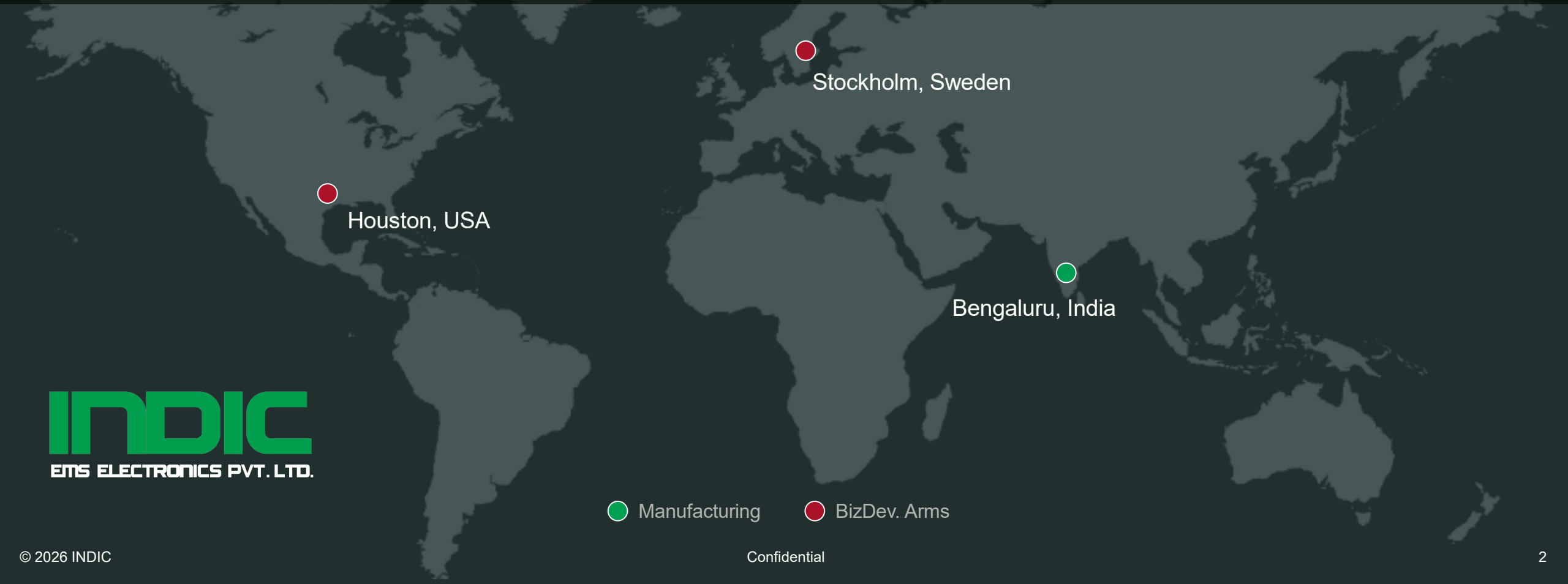


INDIC

EMS ELECTRONICS PVT. LTD.

INDIC is a global leader in Electronics Manufacturing Services (EMS), offering comprehensive lifecycle solutions with an unwavering commitment to the highest standards of quality

Skilled Employees	Gender Diversity (Women)	Square feet of infrastructure	PCB assembled annually	Components placed annually
1600+	70%	292K	10.5M+	19.5B+



INDIC
EMS ELECTRONICS PVT. LTD.

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The INDIC Advantage

Driving success with key differentiators

Governance Stability

Majority Indian stakeholdership
and zero-debt organization

Institutional Support

Benefits from the Indian Govt.
PLI & ‘Make in India’ schemes



Operational Excellence

Scalable & Flexible high
-mix, low-volume solutions

Digital-first Operations

SAP Digital Manufacturing,
S/4HANA, DMS & CalcuQuote

Global Supply Chain

Robust global network,
free from geopolitical risks

Customer Engagement

70-80% of INDIC revenue
share is from export clients

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Vivek Khanna
Founder & Managing Director

INDIC
EMS ELECTRONICS PVT. LTD.



Shirin Khanna
Director - Strategy



Ayush Khanna
Director - Engineering



Basappa Manappa
Chief Financial Officer



Pradeep Nelamangala
SVP - Bus. Dev & Operations



Pradeepa KC.
VP - Supply Chain



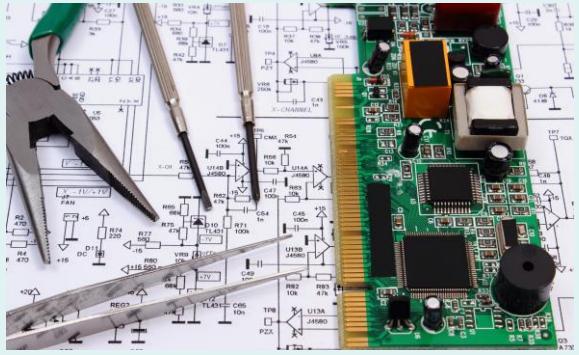
Prateek Srivastava
VP - Engineering & Operations



Vaishnavi Chandran
Chief of Staff

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With quality as our cornerstone, INDIC delivers scalable EMS solutions



NEW PRODUCT INTRODUCTION

Rapid Prototyping, Reverse Engineering, Process Developments, Assembly Tools and Fixture Design



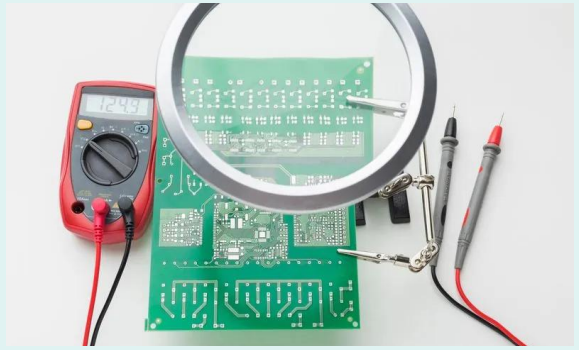
PRODUCT ENGINEERING

Product Development, pFMEA, Component Engg. Product Lifecycle Mgmt., Design for Excellence



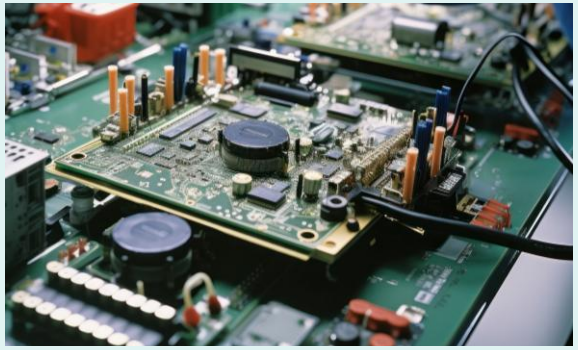
MANUFACTURING SERVICES

Component Sourcing, Assembly Lines, High Value, Low Volume & High Mix PCBA, Soldering, Stenciling



TEST SOLUTIONING & QUALITY

In-House Test Solutioning, Test automation, Test case design, hardware and software architecture definition



CUSTOM BOX-BUILD SOLUTION

Tailored Box-Build Services, Build to Order (BTO), Build to Configure (BTC), System Integration



GLOBAL SUPPLY CHAIN

Integrated Supply Chain, Product Packaging, Shipment Lines, Global Distribution, Last Mile Delivery

ZERO-DEFECT MANUFACTURING

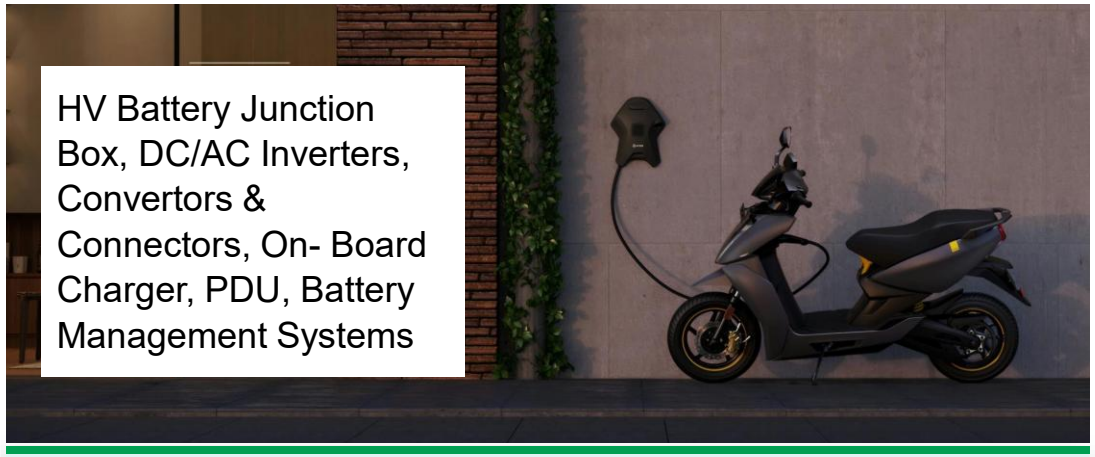
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Our products and expertise across industries



Energy Meters, Zigbee Module, Router -ONG Stations, DC to DC Converters, UPS & Inverters, Drive Controller

RENEWABLES



HV Battery Junction Box, DC/AC Inverters, Convertors & Connectors, On- Board Charger, PDU, Battery Management Systems

E-MOBILITY



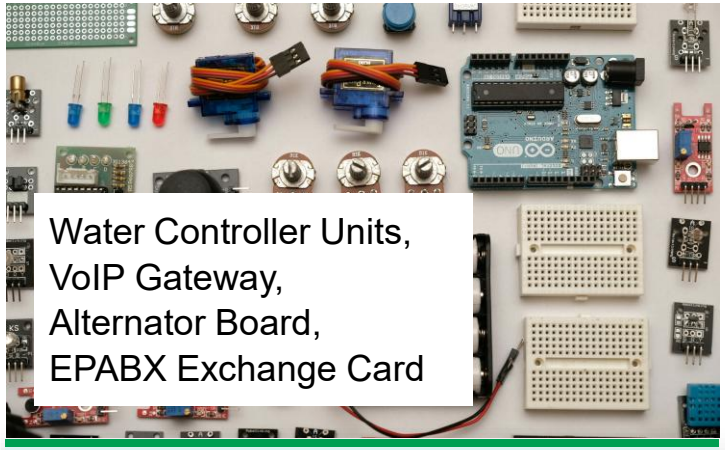
Power Supply, Key Loading Device, Metering Systems, Industrial Circuit Breakers

INDUSTRIAL APPLICATIONS



Electronics for ECU, Sensors, Human Interface Systems, Motor Control Units

AUTOMOTIVE ELECTRONICS



Water Controller Units, VoIP Gateway, Alternator Board, EPABX Exchange Card

OTHER SECTORS

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Product Portfolio

Automotive Electronics

1. Electronics Control Unit & Sensors
2. Human Interface Systems
3. Vehicle / Motor Control Unit
4. Battery Management Systems (BMS)
5. Battery Pack PCBA
6. On-Board & Off-Board Charger / Fast Chargers
7. DC/DC Converters
8. Charging Infrastructure Electronics

Electric Vehicle



Illustrative*

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Process Capabilities

Available | Capability | Future Capability

Technology	Elements	Specifications						
Assembly Process Process	SMT	Single / Double Sided	Rigid Circuits	Flex circuits	Paste in Hole	Nexlev	Mictor	PoP
	Reflow Soldering	Air Reflow			Nitrogen Reflow			
	SMT Chemistry	No-Clean			Clean			
	Wave Soldering	PTH		SMT			Selective Fluxer	
	Wave Chemistry	No-Clean			Clean			
	Cleaning	No-Clean		Bio Act/IPA			Saponifier/DI Water	
	Conformal Coating	Acrylic	Urethane	Silicon	Epoxy Resin		Poly-Para-Xylylene	
	Rework	SRT 1800		Minipot		In-house Developed Tooling		
	Failure Analysis	In-house		3rd Party Laboratories				
Components, PCB	Surface Finish	ENIG	Immersion Tin		HASL		Immersion Silver	OSP
	Board Thickness	32 mils	64 mils		93 mils		125 mils	150 mils
	Via Design	Through Hole		Blind		Buried		Micro Via
	Number of Layers	Up to 12 Layers				> 21 Layers		
Components (Passives)	Size	1206	1008	0805	0603	0402	0201	NEW 01005
Components QFP, TSOP, etc.	Pitch	25 mils		20 mils		16 mils		12 mils
Components BGA	Pitch	0.35 mm NEW		1 mm		1.27 mm		
	I/O	10		up to 676		> 676		
	Package Size	1.9 mm X 2.4 mm		27 mm X 27 mm		> 32 mm X 32 mm		
Components Connector	Lead Type	SMT		PTH		Press Fit		

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Accelerate product success with INDIC's smart manufacturing

Automating procurement with CalcuQuote Supply Chain Management	ERP powered by SAP S/4HANA	Streamlining traceability with SAP Digital Manufacturing	Ensuring compliance with SAP Document Management System
• **Dynamic synchronization across BOMs, inventory, and costing** ensures no surprises from design to delivery.	• **Live production insights feed directly into planning and sourcing decisions,** minimizing downtime and overstock.	• **Instant traceability across linked production, documentation, and test** data, enabling audit readiness & root-cause closure.	• **Connected sourcing decisions driven by real-time production demand**, lead times, and engineering change visibility.
SINGLE PANE OF GLASS	**REMOTE INSIGHTS**	**END-TO-END TRACEABILITY**	
• Faster and more accurate quoting for new SKUs • Early-stage identification of at-risk components • Integrated product costing for mfg. & BoM costing on one platform	• Automated MRP planning tied to real-time inventory data • Integrated vendor & customer master data to reduce redundancy • Clean, auditable records for global compliance	• Unit-level traceability for components, firmware test logs • Consistent build quality across diverse products • Accelerated ramp-up for new product launches	• Ensures only latest client approved files are used • Strict governance of version & revision control • Rapid implementation of engineering changes

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High-spec harness integration with complex PCB assemblies & box-builds

Harness Manufacturing

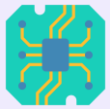


Multibranch cable and wire harnesses - **Optical fiber** assemblies, **Hybrid electrical** wire and **fiber optics** harnesses

Potting, over molding & low pressure molding of assemblies and **custom connectors**; Precision **crimping** and **splicing**

Hi-density harnesses **up to 2500 points**; **3D harnesses** assemblies; Spot welding, **Ultrasonic welding** & Braiding

PCBA Integration



End-to-end traceability from component to finished assembly for **automotive applications**

Automated assembly and **in-circuit testing** for consistent quality assurance

EMI/EMC mitigation through **shielding** and **grounding** best practices

Mechanical Integration



Secure **harness-to-motor mating** for strain relief and **vibration resistance**

Inline testing to validate electrical **continuity** and advance mechanical **fitment**

Packaging & handling processes aligned to **automotive standards**

Harness production standard: IPC 620 Class 2; Class 3 for aerospace or upon request

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Designing Test Solutions

In-House Test Solutioning



- **Test case** design
- Hardware and Software **Architecture Definition**
- Developing & Building **Hardware** and **Software codes**
- **Validation** and **Deployment**
- **Tester** Maintenance & **Upgrades**

Test Automation



- Automation using **LabVIEW**
- **Remote Access** for Diagnostics and Upgrades
- Test & Counter **logs**: **Role Based Access**
- End-to-end **Automated Production Testing**

Real-Time Test Data Access



- **Centralized server** for secure test data storage & backup
- **Access provision to customers to fetch logs** for each product via serial number
- Integrated with **MES** as a **checkpoint**

TEST CAPABILITIES

- In-circuit Testing
- On-board Programming
- Functional Testing
- End-of-line Testing
- Hi-pot Testing
- Reliability Testing

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Environmental Social Governance

Energy efficiency: Replaced halogen fixtures with 100% energy-efficient lighting and installed motion sensor detection to reduce electricity consumption

Water stewardship: Routed surplus treated wastewater from the STP to an authorized recycler in line with regulations

Waste compliance: Disposed e-waste and other regulated waste streams only through authorized recyclers

Adobe Acrobat Document

Diversity, Equity & Inclusion: Women 70% of workforce (FY ended 31 Mar 2025), reflecting inclusive hiring practices

GHG baseline: Already tracking Scope 1 & 2, and establishing a process to track Scope 3 emissions for baseline and ongoing monitoring

WE SUPPORT UN GLOBAL COMPACT

DUN & BRADSTREET ESG REGISTERED™

BRONZE | Top 35% ecovadis Sustainability Rating APR 2026

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What shall we discuss?

THOUGHTS | REQUIREMENTS | SCOPE | TIMELINES

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